

TQP4M9071

High Linearity 6-Bit, 31.5dB Digital Step Attenuator



Mechanical Information

Package Information and Dimensions

This package is lead-free, RoHS-compliant, and green. The plating material on the pins is annealed matte tin over copper. It is compatible with both lead-free (maximum 260 °C reflow temperature) and leaded (maximum 245 °C reflow temperature) soldering processes.

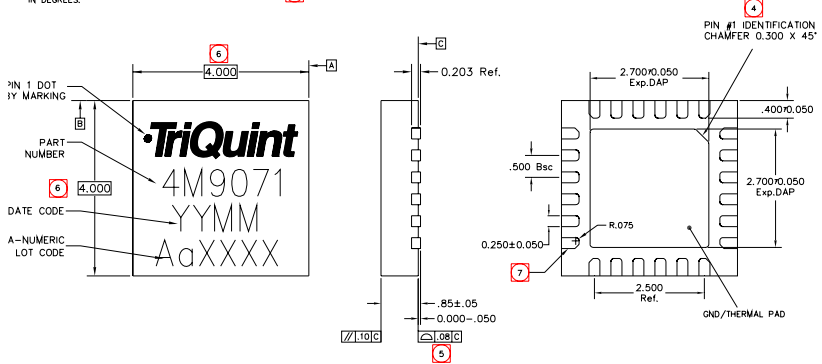
The component will be lasermarked with "4M9071" product label with an alphanumeric lot code on the top surface of the package.

EXCEPT WHERE NOTED, THIS PART OUTLINE CONFORMS TO JEDEC STANDARD MO-229, ISSUE C (VARIATION VUGC) FOR THERMALLY ENHANCED PLASTIC VERY THIN FINE PITCH QUAD FLAT NO LEAD PACKAGE (QFN).

DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.4M-1994.

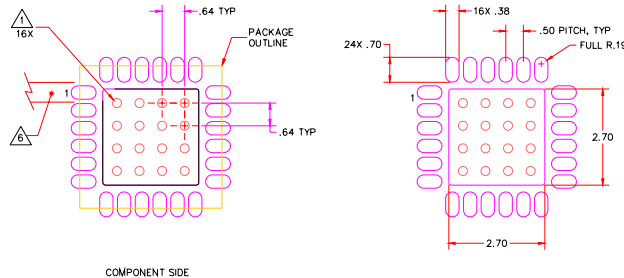
ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.

- 4 THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION CONFORM TO JEDEC 95-1 SPP-012.
- 5 COPLANARITY APPLIES TO THE EXPOSED GROUND/THERMAL PAD AS WELL AS THE TERMINALS.
- 6 PACKAGE BODY LENGTH/WIDTH DOES NOT INCLUDE PLASTIC FLASH PROTRUSION ACROSS MOLD PARTING LINE.
- 7 DEVIATION FROM JEDEC STANDARD MO-229, ISSUE C 12 LEAD COUNT NOT LISTED.



Mounting Configuration

All dimensions are in millimeters (inches). Angles are in degrees.



NOTES:

- 1. GROUND/THERMAL VIAS ARE CRITICAL FOR THE PROPER PERFORMANCE OF THIS DEVICE. VIAS SHOULD USE A .35mm (#80/.0135") DIAMETER DRILL AND HAVE A FINAL PLATED THRU DIAMETER OF .25mm (.010").
- 2. ADD AS MUCH COPPER AS POSSIBLE TO INNER AND OUTER LAYERS NEAR THE PART TO ENSURE OPTIMAL THERMAL PERFORMANCE.
- 3. TO ENSURE RELIABLE OPERATION, DEVICE GROUND PADDLE-TO-GROUND PAD SOLDER JOINT IS CRITICAL.
- 4. ADD MOUNTING SCREWS NEAR THE PART TO FASTEN THE BOARD TO A HEATSINK. ENSURE THAT THE GROUND/THERMAL VIA REGION CONTACTS THE HEATSINK.
- 5. DO NOT PUT SOLDER MASK ON THE BACK SIDE OF THE PC BOARD IN THE REGION WHERE THE BOARD CONTACTS THE HEATSINK.
- 6. RF TRACE WIDTH DEPENDS UPON THE PC BOARD MATERIAL AND CONSTRUCTION.
- 7. USE 1 OZ. COPPER MINIMUM.
- 8. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.

Notes:

- 1. Ground / thermal vias are critical for the proper performance of this device. Vias should use a .35mm (#80 / .0135") diameter drill and have a final plated thru diameter of .25 mm (.010").
- 2. Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.